



## Material Content Data Sheet



<b>Sales Product Name</b>	BSL372SN H6327			<b>Issued</b>	23. January 2018			
<b>MA#</b>	MA001218058							
<b>Package</b>	PG-TSOP6-6-6			<b>Weight*</b>	13.65 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.011	0.08		780	
	noble metal	gold	7440-57-5	0.041	0.30		3024	
	inorganic material	silicon	7440-21-3	0.630	4.61	4.99	46129	49933
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		433	
	non noble metal	chromium	7440-47-3	0.018	0.13		1298	
	non noble metal	copper	7440-50-8	5.882	43.10	43.28	430879	432697
wire	non noble metal	copper	7440-50-8	0.058	0.42	0.42	4217	4217
encapsulation	organic material	carbon black	1333-86-4	0.065	0.48		4783	
	plastics	epoxy resin	-	1.404	10.28		102844	
	inorganic material	silicondioxide	60676-86-0	5.061	37.07	47.83	370716	478343
leadfinish	non noble metal	tin	7440-31-5	0.299	2.19	2.19	21896	21896
plating	noble metal	silver	7440-22-4	0.176	1.29	1.29	12914	12914
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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